EP2C+

2 Way-0°  $50\Omega$ 

1800 to 12500 MHz

# **The Big Deal**

- Ultra-Wide Bandwidth, 1800-12500 MHz
- Tiny Size, 4 x 4 x 1 mm
- High Power Handling, 1.85W as a Splitter



### **Product Overview**

Mini-Circuits EP2C+ is a MMIC splitter/combiner designed for wideband operation from 1800 to 12500 MHz. This model provides excellent power ratings in a tiny device package (4x4x1 mm), with up to 1.85W power handling (as a splitter) and up to 0.4A DC current handling. Manufactured using GaAs IPD technology, it provides a high level of ESD protection and excellent reliability.

# **Key Features**

Feature	Advantages			
Wideband, 1800 to 12500 MHz	One power splitter can be used in many applications, saving component count. Also ideal for wideband applications such as military and instrumentation.			
Excellent power handling 1.85W as a splitter 0.85W internal dissipation as a combiner	In power combiner applications, half the power is dissipated internally. EP2C+ is designed to handle 0.85W internal dissipation as a combiner allowing reliable operation without excessive temperature rise. Similar splitters implemented as Wilkinson splitters on PCB require big resistors and additional heat sinking.  As a splitter, EP2C+ can handle up to 1.85W in a very small package.			
DC Passing up to 0.4A	DC current passing is helpful in applications where both RF & DC need to pass through the DUT, such as antenna mounted hardware.			
Small size 4 x 4mm QFN package	Tiny footprint saves space in dense layouts while providing low inductance, repeatable transitions, and excellent thermal contact to the PCB.			

# ower Splitter/Combiner

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#### **Features**

- Wide bandwidth, 1800 to 12500 MHz
- Excellent amplitude unbalance, 0.2 dB typ.
- Good phase unbalance, 6 deg. typ.
- Small size, 4x4 mm
- High ESD level\*
- Aqueous washable
- DC passing

## **Applications**

- WIMAX
- ISM
- Instrumentation
- Radar
- WLAN
- Satellite communications
- LTE

#### Electrical Specifications at 25°C

Generic photo used for illustration purposes only

CASE STYLE: DG1847

+RoHS Compliant
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Parameter	Frequency (MHz)	Min.	Тур.	Max.	Unit
Frequency Range		1800		12500	MHz
	1800-3800	_	0.8	1.1	
Insertion Loss, above 3.0 dB	3800-8500	_	1.1	1.4	dB
	8500-12500	_	1.8	2.1	
	1800-3800	7.0	10.0	_	
Isolation	3800-8500	13.0	16.0	_	dB
	8500-12500	14.0	17.0	_	
	1800-3800	_	3.0	6.0	
Phase Unbalance	3800-8500	_	6.0	10.0	Degree
	8500-12500	_	11.0	_	
	1800-3800	_	0.1	0.2	
Amplitude Unbalance	3800-8500	_	0.2	0.4	dB
	8500-12500	_	0.7	0.9	
VSWR (Port S)	1800-3800	_	1.5	_	
	3800-8500	_	1.3	_	:1
	8500-12500	_	1.4	_	
	1800-3800	_	1.2	_	
VSWR (Port 1-2)	3800-8500	_	1.3	_	:1
	8500-12500	_	1.6	_	

#### **Maximum Ratings**

Parameter	Ratings
Operating Temperature	-40°C to 85°C
Storage Temperature	-65°C to 150°C
Power Input (as a splitter)	1.85 W max.
Internal Dissipation	0.85 W max.
DC Current	0.4 A max

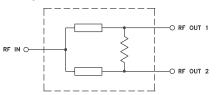
Permanent damage may occur if any of these limits are exceeded.

Human body model (HBM): Class 2(1800 to <4000 V) in accordance with ANSI/ESD 5.1-2007 Machine model (MM): Class M3 (200 to <400 V) in accordance with ANSI/ESD 5.2-2009

#### **Pad Connections**

Function	Pad Number		
SUM PORT	3		
PORT 1	19		
PORT 2	12		
NOT USED, GROUND EXTERNALLY	1, 2, 4-11, 13-18, 20-24, Paddle		

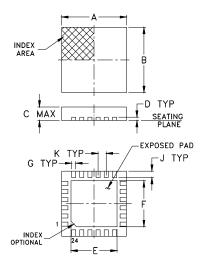
#### Simplified Electrical Schematic



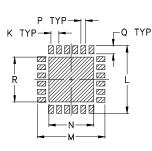


<sup>\*</sup> ESD rating

#### **Outline Drawing**



#### **PCB Land Pattern**



Suggested Layout, Tolerance to be within  $\pm .002$ 

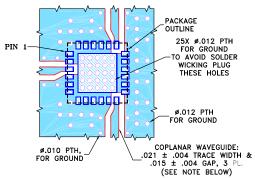
#### **Product Marking**



#### Outline Drawing Dimensions (inch)

J	Н	G	F	E	D	С	В	Α
.016		.009	.104	.104	.008	.039	.157	.157
0.41		0.23	2.64	2.64	0.20	1.0	4.0	4.0
wt		R	Q	Р	N	М	L	K
grams		.102	.020	.012	.102	.166	.166	.020
0.04		2.59	0.51	0.30	2.59	4.22	4.22	0.50

#### Demo Board MCL P/N: TB-811+ Suggested PCB Layout (PL-442)



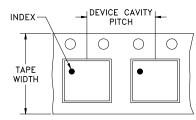
- 1. COPLANAR WAVEGUIDE IS SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .010" ± .001". COPPER: 1/2 0Z. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED. 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

  DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).

DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

#### Tape and Reel (F68)

DEVICE ORIENTATION IN T&R



DIRECTION OF FEED

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel see note	
12	8	7	Small quantity standard	20 50 100 200 500
		7	Standard	1000
		13	Standard	2000 3000 4000